



# IEEE International Conference on IC Design & Technology

Dresden, Germany, Sept 15<sup>th</sup> – 17<sup>th</sup>, 2021

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## Conference Sponsors



Design-technology co-optimization is the key to success in the highly competitive market today. Traditional integrated circuit (IC) engineering separates design and technology, each employing their own language and rarely understand each other. Now, a savvy IC engineer needs to understand the interdependencies between design and technology options to expand the product optimization window. ICICDT is, by design, a forum for engineers, researchers, graduate students and professors, to cross the design-technology boundary by bringing design, technology, and process experts together. This conference has been organized by worldwide committee members from industry and academia since 2003.

We are excited to see what the unique format looks like as a virtual event. We will keep the tradition that each paper has a short prerecorded presentation available on demand and there will be new ways for posters and Q&A. Be curious!

### Venue:

The 2021 IEEE International Conference on IC Design and Technology (ICICDT) goes virtual. We will send out the link closer to the event.

## Contributed papers are solicited in the following subject areas:

- Emerging technologies and Applications (MEMS, Internet of Things, Autonomous cars, Machine Learning, Artificial Intelligence, Alternative Computing, Quantum Computing etc.);
- Security technologies (true random number generator, physically uncloneable function etc.);
- Advanced materials and processing technologies, power semiconductor technologies and circuits;
- Advanced transistor and interconnect structures;
- Advanced Packaging, vertical (2.5D/3D) integration, bandwidth and signal integrity;
- Emerging and novel memory technology and system;
- Variation and fault-tolerant designs, reliability issues and mitigation approaches, EDA and design optimizations across system, circuit, and/or device levels for high performance, energy efficiency, yield, and/or reliability;
- RF, analog, mixed signal, and I/O circuits for future technology generations;
- Simulation and modeling of advanced processes, devices, and circuits;
- Design for manufacturing, yield, and test;
- Design for System-on-Chip (SoC), system-in-package (SiP) and advance 2.5D/3D technology

**Paper Submission Deadline: May 5<sup>th</sup>, 2021**

## 2021 ICICDT Executive Committee Members

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